

The 2nd IEICE MWPTHz Symposium

Call for Papers and Participation

Researchers working in microwave photonics, terahertz technologies, and photonics-related fields are invited to participate in this international symposium, bringing together researchers primarily from Japan and Taiwan. Young researchers and students are especially encouraged to join.

Date	November 23–24, 2026
Venue	ACE Biotech Conference Room and Entrance Hall, Hsinchu, Taiwan
Topics	Microwave Photonics, Terahertz Technologies, and Photonics-related Technologies



Venue (ACE Biotech)



Participants at Last Year's Symposium (Taipei)

Two Days of Technical Presentations and Networking Opportunities

Technical Program ● Keynote Presentation : 50 min × 1 ● Invited Talks : 30 min × 4 ● Oral Presentations : 20 min × 15 ● Poster Presentations : 30	Important Dates ● September 28, 2026: Presentation Application Deadline ● New: October 10, 2026 (Saturday): Presentation Application Deadline ● October 23, 2026 (Friday): Manuscript Deadline ● November 23, 2026: Technical Sessions and Banquet ● November 24, 2026: Technical Sessions and Technical Tour
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Keynote Speaker

The Future of Terahertz Technologies: High-Speed Links and Integrated Photonic Systems



Tadao Nagatsuma (The University of Tokyo; Professor Emeritus, The University of Osaka; IEEE Life Fellow; IEICE Fellow and Honorary Member.)

Recent developments in THz devices, photonic generation techniques, and wideband circuits have enabled short-range links exceeding 100 Gb/s and high-resolution sensing capabilities. Although THz frequencies may play a limited role in wide-area mobile networks, their importance in semiconductor-centric architectures is growing. Heterogeneous integration, silicon photonics, and co-packaged optics (CPO) provide new pathways for THz-band interconnects, THz-over-fiber systems, and high-resolution sensing for materials, devices, and integrated systems. These directions highlight THz as a versatile technology that integrates communication, sensing, and photonics within next-generation semiconductor platforms. This presentation will review recent achievements and discuss emerging THz applications for integrated systems in the 2030s.